

eS32 e-beam inspection



eS32 System Configuration

- ◆ **iADC** (inline Automated Defect Classification)
- ◆ **WAFER HANDLER CONFIGURATION**
 - 200 mm SMIF
 - 300 mm FOUP
 - 300 mm FOUP with 200mm insert
 - 200 mm and/or 300 mm Open Cassette
- ◆ **200 mm/300 mm COMBINED CONFIGURATION**

The system can be configured to accommodate 200mm / 300mm wafers. The eS32, with Hybrid Port control allows support of concurrent 200mm and 300mm load ports. For sites with Factory Automation, switching between the two requires a shutdown and restart of the software to load the proper configuration file.

- ◆ **Standard pixel sizes**

eS32: 0.025, 0.035, 0.05, 0.07, 0.10, 0.15, 0.20, and 0.30 μ m.

- ◆ **Inspection modes**

- Array Mode (Cell-to-Cell)
- Random Mode (Die-to-Die)
- Master Reference Inspection (Die-to-Any Die)

eS32 Specifications

Item	MTBF	MTTRf		MTB A	Supplier dependant uptime
		Vacuum	Non- vacuum		
SPEC	> 500hrs	< 12hrs	< 8hrs	>96hrs	>95%